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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 35010.8-2018

**Semiconductor die products -- Part 8: EXPRESS model schema
for data exchange**

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Table of Contents

- Foreword
- 1 Scope
- 2 Normative references
- 3 Terms and definitions
- 4 General

Foreword

GB/T 35010 "Semiconductor Chip Products" is divided into the following parts.

- Part 1. Procurement and use requirements;
- Part 2. Data exchange format;
- Part 3. Guidelines for handling, packaging and storage;
- Part 4. Chip user and supplier requirements;
- Part 5. Electrical Simulation Requirements;
- Part 6. Thermal Simulation Requirements;
- Part 7. XML format for data exchange;
- Part 8. EXPRESS format for data exchange.

This part is Part 8 of GB/T 35010.

This section uses the translation method equivalent to the use of IEC /T R62258-8.2008 "semiconductor chip products part 8. data exchange

EXPRESS format.

The Chinese documents that have a consistent correspondence with the normatively quoted international documents in this section are as follows.

- GB/T 2900 (all parts) Electrotechnical terminology [IEC 60050 (all parts)];
- GB/T 35010.1-2018 Semiconductor chip products Part 1. Procurement and use requirements (IEC 62258-1.2009, IDT);
- GB/T 35010.2-2018 Semiconductor chip products Part 2. Data exchange format (IEC 62258-2.2011,

IDT);

---GB/T 35010.4-2018 Semiconductor chip products Part 4. Chip user and supplier requirements (IEC /TR

62258-4.2012,IDT);

--- GB/T 35010.5-2018 semiconductor chip products - Part 5. Electrical simulation requirements (IEC 62258-5.2006,

IDT);

---GB/T 35010.6-2018 Semiconductor chip products Part 6. Thermal simulation requirements (IEC 62258-6.2006, IDT).

This section made the following editorial changes.

--- Deleted the description of the download material in the last paragraph of "Dataexchange" in IEC /T R62258-8.

This section was proposed by the Ministry of Industry and Information Technology of the People's Republic of China.

This part is under the jurisdiction of the National Semiconductor Device Standardization Technical Committee (SAC/TC78).

This section was drafted by. Tsinghua University, 58th Institute of China Electronics Technology Group Corporation, Inspur (Beijing) Electronic Information Industry

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1 Scope

This part of GB/T 35010 is used to guide the production, supply and use of semiconductor chip products. One of the semiconductor chip products includes.

- * Wafers;
- * Single bare chip;
- * Chips and wafers with interconnect structures;
- * Smallest or partially packaged chips and wafers.

This section specifies the EXPRESS format for the elements required for data exchange; meets IEC 62258-1, IEC 62258-5 and IEC 62258-

Implementation requirements for 6; Supplement the data exchange structure defined in IEC 62258-2; Compatible and supplement the information sheet in IEC 62258-4.

2 Normative references

The following documents are indispensable for the application of this document. For dated references, only dated versions apply to this article

Pieces. For undated references, the latest version (including all amendments) applies to this document.

GB/T 16656.11-2010 Industrial automation system and integrated product data expression and exchange Part 11. Description method.

EXPRESS Language Reference Manual (ISO 10303-11:2004, IDT)

GB/T 16656.21-2008 Industrial automation systems and integrated product data expression and exchange Part 21. Implementation methods.

Pure text encoding of the exchange file structure (ISO 10303-21:2002, IDT)

IEC 60050 (all parts) International Electrotechnical Vocabulary

IEC 62258-1 Semiconductor chip products Part 1. Procurement and use requirements (Semiconductor die products-Part 1.

Requirements for procurement and use)

IEC 62258-2 Semiconductor chip products Part 2. Data interchange formats (Semiconductor die products-Part 2.

Exchanged data formats)

IEC 62258-4 Semiconductor chip products Part 4. Chip user and supplier requirements (Semiconductor die prod-

ucts-Part 4. Questionnaire for die users and suppliers)

IEC 62258-5 Semiconductor chip products - Part 5. Electrical simulation requirements (Semiconductor die products-Part 5.

Requirements for information concerning electrical simulation)

IEC 62258-6 Semiconductor Chip Product Part 6. Thermal Simulation Requirements (Semiconductor die products-Part 6.

Requirements for information concerning thermal simulation)

3 Terms and definitions

The terms and definitions defined by IEC 60050 (all parts) and IEC 62258-1 apply to this document.

4 General

The EXPRESS format in this section follows GB/T 16656.11-2010, allowing the use of GB/T 16656.21-2008 defined

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